



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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SURFBOARDS®



THE BREADBOARDING MEDIUM FOR **SURFACE MOUNT**™

33000 SERIES APPLICATION SPECIFIC ADAPTERS

IDS33003

REV 1-2012

MODEL **33003**

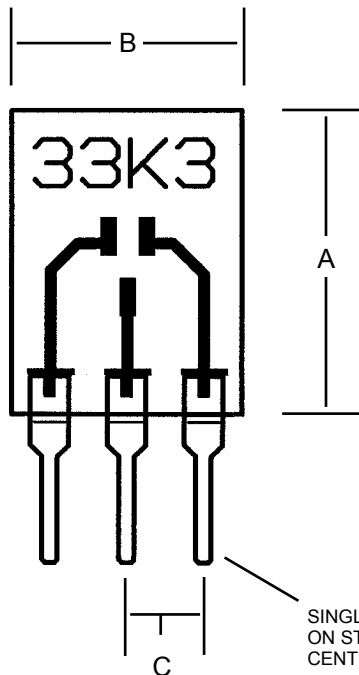
ACCEPTS
(PARTIAL LISTING)

SC-70-3
SOT-323
ANALOG KS-3
CENTRAL SUPERMINI™ *
DOIDES INC. DFN322 *1
NEC PKG No. 30
ON SEMI CASE 419-AB-01
RENESAS SSP
TOSHIBA UFM / USM

ALWAYS CONSULT DEVICE DATA SHEET TO INSURE PROPER FIT

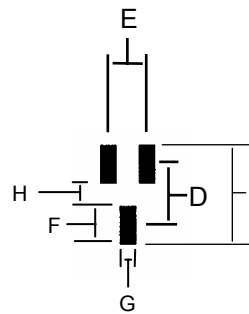
PINS ON .100 in. CENTERS
PROVIDE COMPATIBILITY WITH
CONVENTIONAL AND
SOLDERLESS BREADBOARDS AND
SOCKETS.

USE FOR PROTOTYPING,
DEVICE TEST OR EVALUATION,
SMD TO THROUGH HOLE
CONVERSION



SEE WEBSITE FOR
SOLDERING
SUGGESTIONS

DEVICE FOOTPRINT



SINGLE-IN-LINE (SIP) PINS
ON STANDARD .100 IN.
CENTERS. SEE PIN SPECS.

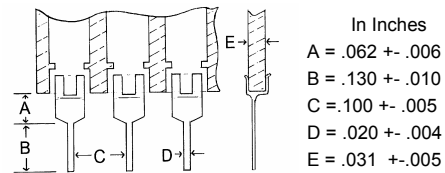
FIG.	INCHES	MM	NOTE:
A	.400	10.16	BOARD HEIGHT +/- .5mm .020in.
B	.300	7.62	BOARD WIDTH +/- .5mm .020in.
C	.100	2.54	SIP PIN SPACE +/- .20mm .008in.
D	.080	2.03	PAD CENTERLINE
E	.0512	1.30	DEVICE LEAD PITCH
F	.050	1.27	PAD LENGTH
G	.020	.508	PAD WIDTH
H	.030	.76	GAP
I	.130	3.30	MAX LEAD WIDTH

NOTE *1
This device
must be
mounted
offset to
avoid
shorting of
pads.



* Supermini is a
Trademark of Central
Semiconductor Corp.

PIN SPECIFICATIONS / TOLERANCES



In Inches
A = .062 +/- .006
B = .130 +/- .010
C = .100 +/- .005
D = .020 +/- .004
E = .031 +/- .005

BOARD SPECIFICATIONS

BOARD MATERIAL: .8mm, +/- .13mm .031in+/- .005 in.
Thick G-10 FR-4 Glass Epoxy or equivalent.
CIRCUITS: 1 oz. Copper with RoHS compliant Lead
Free solder coating. Patten Position on board +/-
.5mm .020in.

TOLERANCES: If not noted are +/- 20%. Nominal values are given.
Controlling unit is Millimeters. Values rounded to nearest decimal. Slight
Variations due to manufacturing process can occur.

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